MA379

Silicon epitaxial planer type

For UHF tuner

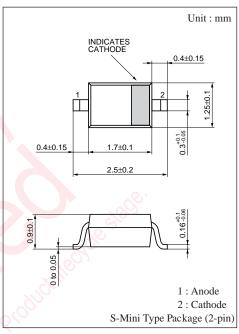
■ Features

- Large capacity variation ratio
- Small series resistance r_D
- S-Mini package, enabling down-sizing of the equipment and automatic insertion through taping

■ Absolute Maximum Ratings (Ta= 25°C)

Parameter	Symbol	Rating	Unit	
Reverse voltage (DC)	V _R	32	V	
Peak reverse voltage	V _{RM} *	35	V	
Junction temperature	Tj	150	°C	
Storage temperature	T_{stg}	- 55 to +150	°C	

^{*} $R_L=10k\Omega$



Marking Symbol: 7L

■ Electrical Characteristics (Ta= 25°C)

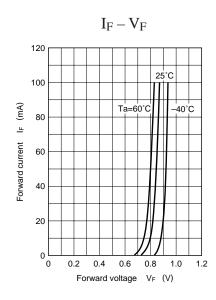
Parameter	Symbol	Condition	min typ	max	Unit
Reverse current (DC)	I _R	$V_R = 30V$	100 TO 5	10	nA
Diode capacitance	C _{D(2V)}	$V_R = 2V$, $f = 1MHz$	5.50	6.84	pF
	C _{D(25V)}	$V_R = 25V$, $f = 1MHz$	0.84	1.05	pF
	C _{D(10V)}	$V_R = 10V$, $f = 1MHz$	1.80	2.38	pF
	C _{D(17V)}	$V_R = 17V$, $f = 1MHz$	1.03	1.36	pF
Capacitance ratio	C _{D(2V)} /C _{D(25V)}	Ma Jis.	6.0	7.0	_
Diode capacitance deviation	ΔC	C _{D (2V) (10V) (17V) (25V)}		2.0	%
Series resistance	r _D *	$V_R = 5V$, $f = 470MHz$		1.0	Ω

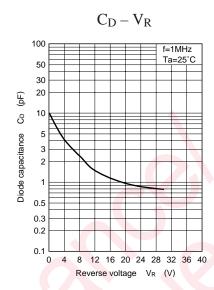
Note 1. Rated input/output frequency: 470MHz

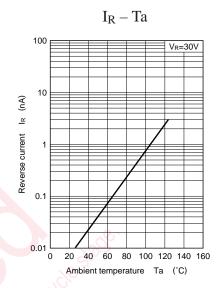
■ Marking

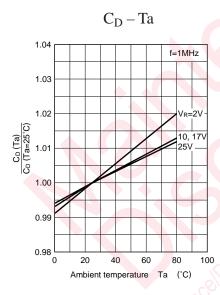


^{2. *} rD measurement device : YHP MODEL 4191A RF IMPEDANCE ANALYZER









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